

# **PHOTOCOUPLER**

# PS9513,PS9513L1,PS9513L2,PS9513L3

# 1 Mbps, OPEN COLLECTOR OUTPUT, FOR GATE DRIVE INTERFACE INTELLIGENT POWER MODULE 8 mm CREEPAGE 8-PIN DIP HIGH-SPEED PHOTOCOUPLER

-NEPOC Series-

#### **DESCRIPTION**

The PS9513L1, PS9513L2 and PS9513L3 are optically coupled isolators containing a GaAlAs LED on the input side and a photo diode and a signal processing circuit on the output side on one chip.

The PS9513 is designed specifically for high common mode transient immunity (CMR) and low pulse width distortion with operating temperature. It is suitable for IPM drive.

The PS9513L1 is lead bending type for long creepage distance.

The PS9513L2 is lead bending type for long creepage distance (Gull-wing) for surface mount.

The PS9513L3 is lead bending type (Gull-wing) for surface mounting.

#### **FEATURES**

- Long creepage distance (8 mm MIN.: PS9513L1, PS9513L2)
- High common mode transient immunity (CMH, CML =  $\pm 15 \text{ kV/}\mu\text{s MIN.}$ )
- High-speed response (tphL = 500 ns MAX., tplH = 750 ns MAX.)
- Maximum propagation delays (tplh tphL = 270 ns TYP.)
- Pulse width distortion ( | tPHL tPLH | = 270 ns TYP.)
- · Open collector output
- Ordering number of tape product: PS9513L2-E3: 1 000 pcs/reel

: PS9513L3-E3 : 1 000 pcs/reel

- Pb-Free product
- Safety standards

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- UL approved: No. E72422
- CSA approved: No. CA 101391 (CA5A, CAN/CSA-C22.2 60065, 60950)
- BSI approved: No. 8937, 8938
- · SEMKO approved: No. 615433
- · NEMKO approved: No. P06207243
- · DEMKO approved: No. 314091
- FIMKO approved: No. FI 22827
- DIN EN60747-5-2 (VDE0884 Part2) approved: No. 40019182 (Option)

# **APPLICATIONS**

- IPM Driver
- · General purpose inverter

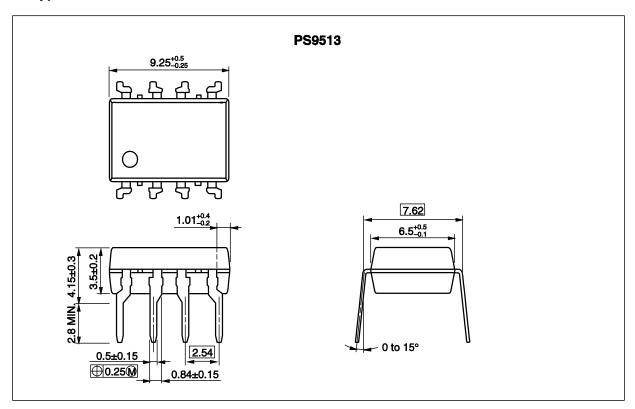
PIN CONNECTIONS
(Top View)

1. NC
2. Anode
3. Cathode
4. NC
5. GND
6. Vo
7. NC
1 2 3 4 8. Vcc

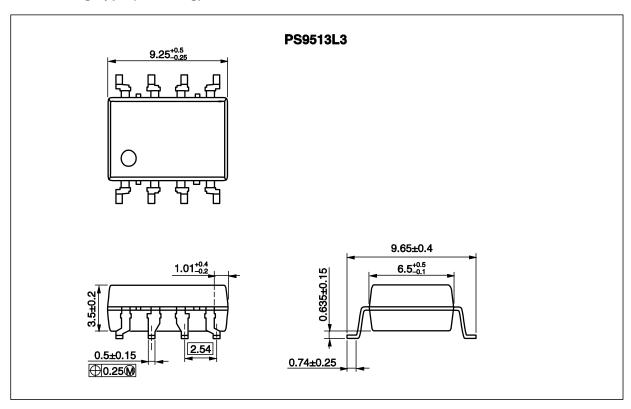
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# <R> PACKAGE DIMENSIONS (UNIT: mm)

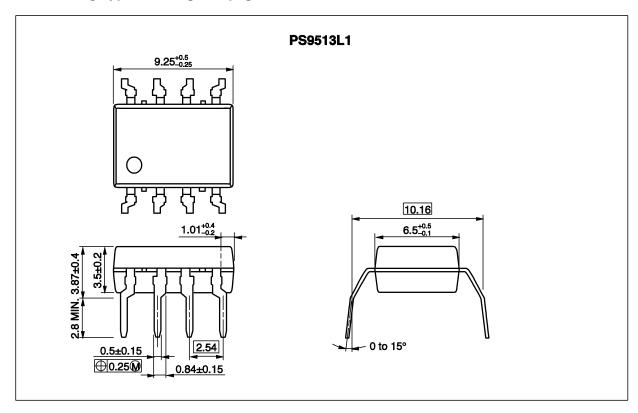
# **DIP Type**



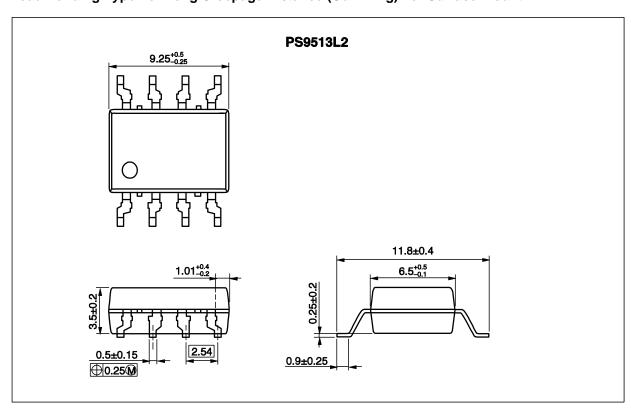
# Lead Bending Type (Gull-wing) For Surface Mount



# **Lead Bending Type For Long Creepage Distance**



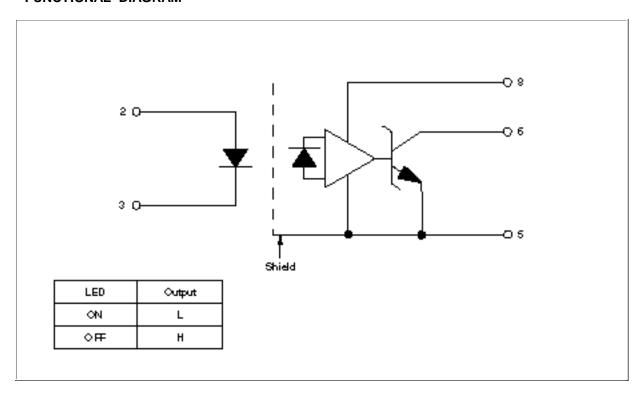
# Lead Bending Type For Long Creepage Distance (Gull-wing) For Surface Mount



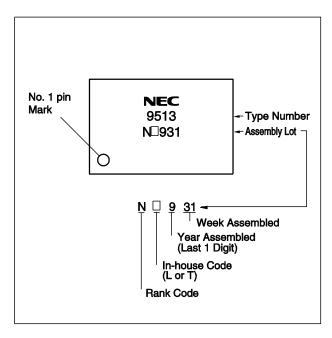
#### PHOTOCOUPLER CONSTRUCTION

Parameter	PS9513, PS9513L3	PS9513L1, PS9513L2
Air Distance (MIN.)	7 mm	8 mm
Outer Creepage Distance (MIN.)	7 mm	8 mm
Isolation Distance (MIN.)	0.4 mm	0.4 mm

# **FUNCTIONAL DIAGRAM**



#### <R> MARKING EXAMPLE



# ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number* <sup>1</sup>
PS9513	PS9513-AX	Pb-Free	Magazine case 50 pcs	Standard products	PS9513
PS9513L1	PS9513L1-AX	(Ni/Pd/Au)		(UL, CSA, BSI,	PS9513L1
PS9513L2	PS9513L2-AX			SEMKO, NEMKO,	PS9513L2
PS9513L3	PS9513L3-AX			DEMKO, FIMKO	PS9513L3
PS9513L2-E3	PS9513L2-E3-AX		Embossed Tape 1 000 pcs/reel	approved)	PS9513L2
PS9513L3-E3	PS9513L3-E3-AX				PS9513L3
PS9513-V	PS9513-V-AX		Magazine case 50 pcs	DIN EN60747-5-2	PS9513
PS9513L1-V	PS9513L1-V-AX			(VDE0884 Part2)	PS9513L1
PS9513L2-V	PS9513L2-V-AX			Approved (Option)	PS9513L2
PS9513L3-V	PS9513L3-V-AX				PS9513L3
PS9513L2-V-E3	PS9513L2-V-E3-AX		Embossed Tape 1 000 pcs/reel		PS9513L2
PS9513L3-V-E3	PS9513L3-V-E3-AX				PS9513L3

<sup>\*1</sup> For the application of the Safety Standard, following part number should be used.

# ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

	Parameter	Symbol	Ratings	Unit
Diode	Forward Current*1	lF	25	mA
	Reverse Voltage	VR	5.0	V
Detecto r	Supply Voltage	Vcc	-0.5 to +35	V
	Output Voltage	Vo	-0.5 to +35	V
	Output Current	lo	15	mA
	Power Dissipation*2	Pc	100	mW
Isolation	Voltage <sup>⁺3</sup>	BV	5 000	Vr.m.s.
Operatino	g Ambient Temperature	TA	-40 to +100	°C
Storage	Temperature	T <sub>stg</sub>	–55 to +125	°C

<sup>\*1</sup> Reduced to 0.33 mA/ $^{\circ}$ C at T<sub>A</sub> = 70 $^{\circ}$ C or more.

#### RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Forward Current	lF	10		20	mA
Output Voltage	Vo	0		30	V
Supply Voltage	Vcc	4.5	15	30	V
Input Voltage	VF	0		0.8	V

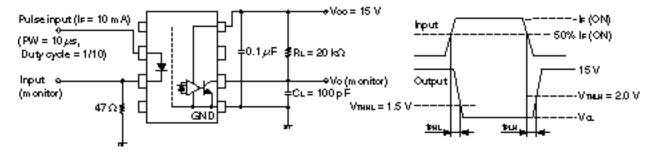
<sup>\*2</sup> Reduced to 2.0 mW/ $^{\circ}$ C at T<sub>A</sub> = 70 $^{\circ}$ C or more.

<sup>\*3</sup> AC voltage for 1 minute at  $T_A = 25^{\circ}C$ , RH = 60% between input and output. Pins 1-4 shorted together, 5-8 shorted together.

# ELECTRICAL CHARACTERISTICS ( $T_A = -40 \text{ to } +100^{\circ}\text{C}$ , $V_{CC} = 15 \text{ V}$ , unless otherwise specified)

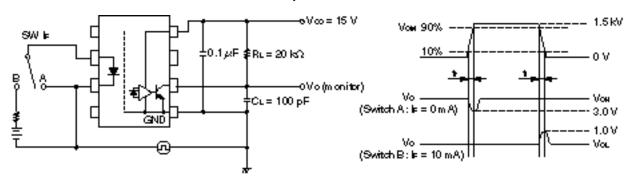
	Parameter	Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA	1.3	1.65	2.1	V
	Reverse Current	lr	VR = 3 V			200	μA
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz, T <sub>A</sub> = 25°C		30		pF
Detector	Low Level Output Voltage	Vol	IF = 10 mA, IoL = 2.4 mA		0.13	0.6	V
	High Level Output Current	Іон	Vcc = 30 V, V <sub>F</sub> = 0.8 V		1.0	50	μA
	High Level Supply Current	Іссн	Vcc = 30 V, V <sub>F</sub> = 0.8 V, V <sub>O</sub> = open		0.6	1.3	mA
	Low Level Supply Current	Iccl	Vcc = 30 V, IF = 10 mA, Vo = open		0.6	1.3	mA
Coupled	Threshold Input Current $(H \rightarrow L)$	İFHL	Vo = 0.8 V, Io = 0.75 mA		0.86	5.0	mA
	Current Transfer Ratio (Ic/IF)	CTR	IF = 10 mA, Vo = 0.6 V	44	110		%
	Isolation Resistance	Ri-o	V <sub>FO</sub> = 1 kV <sub>DC</sub> , RH = 40 to 60%, T <sub>A</sub> = 25°C	10 <sup>11</sup>			Ω
	Isolation Capacitance	Сю	V = 0 V, f = 1 MHz, T <sub>A</sub> = 25°C		0.7		pF
	Propagation Delay Time $(H \rightarrow L)^{*2}$	<b>t</b> PHL	$I_F = 10 \text{ mA}, \ R_L = 20 \text{ k}\Omega, \ C_L = 100 \text{ pF},$ $V_{THHL} = 1.5 \text{ V}, \ V_{THLH} = 2.0 \text{ V}$		250	500	ns
	Propagation Delay Time $(L \rightarrow H)^{*2}$	tрLН			520	750	
	Maximum Propagation Delays	tрин—tрни		-200	270	650	
	Pulse Width Distortion (PWD)*2	tphl=tplh			270	650	
	Common Mode Transient Immunity at High Level Output <sup>*3</sup>	СМн	$T_{A} = 25^{\circ}C, \ I_{F} = 0 \ mA, \ V_{O} > 3.0 \ V,$ $V_{CM} = 1.5 \ kV, \ R_{L} = 20 \ k\Omega,$ $C_{L} = 100 \ pF$	15			kV/µs
	Common Mode Transient Immunity at Low Level Output <sup>*3</sup>	CML	$T_{A} = 25^{\circ}C, \ I_{F} = 10 \ mA, \ V_{O} < 1.0 \ V,$ $V_{CM} = 1.5 \ kV, \ R_{L} = 20 \ k\Omega,$ $C_{L} = 100 \ pF$	15			kV/µs

- \*1 Typical values at T<sub>A</sub> = 25°C.
- \*2 Test circuit for propagation delay time



Ou includes probe and stray wiring capacitance.

\*3 Test circuit for common mode transient immunity



Outnotudes probe and stray wiring capacitance.

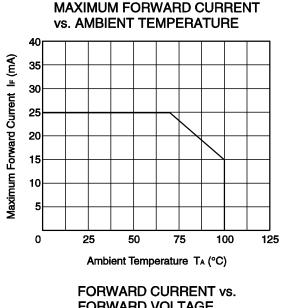
#### **USAGE CAUTIONS**

- 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- 2. By-pass capacitor of more than 0.1  $\mu$ F is used between Vcc and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. Pins 1, 4 (which is an NC<sup>\*1</sup> pin) can either be connected directly to the GND pin on the LED side or left open. Also, Pin 7 (which is an NC<sup>\*1</sup> pin) can either be connected directly to the GND pin on the detector side or left open.

Unconnected pins should not be used as a bypass for signals or for any other similar purpose because this may degrade the internal noise environment of the device.

- \*1 NC: Non-Connection (No Connection)
- 4. Avoid storage at a high temperature and high humidity.

#### TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)



vs. AMBIENT TEMPERATURE

150

(MW) od up 100

50

50

**DETECTOR POWER DISSIPATION** 

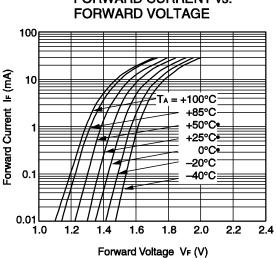
Ambient Temperature TA (°C)
SUPPLY CURRENT vs.

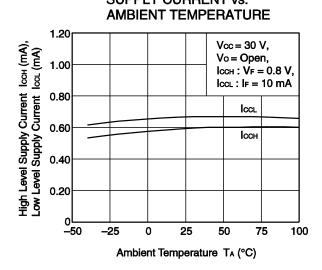
125

50

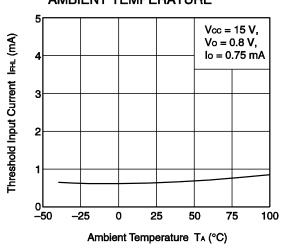
0

25

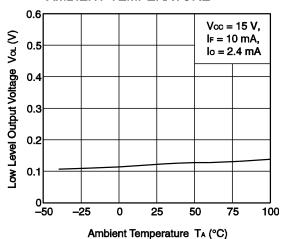




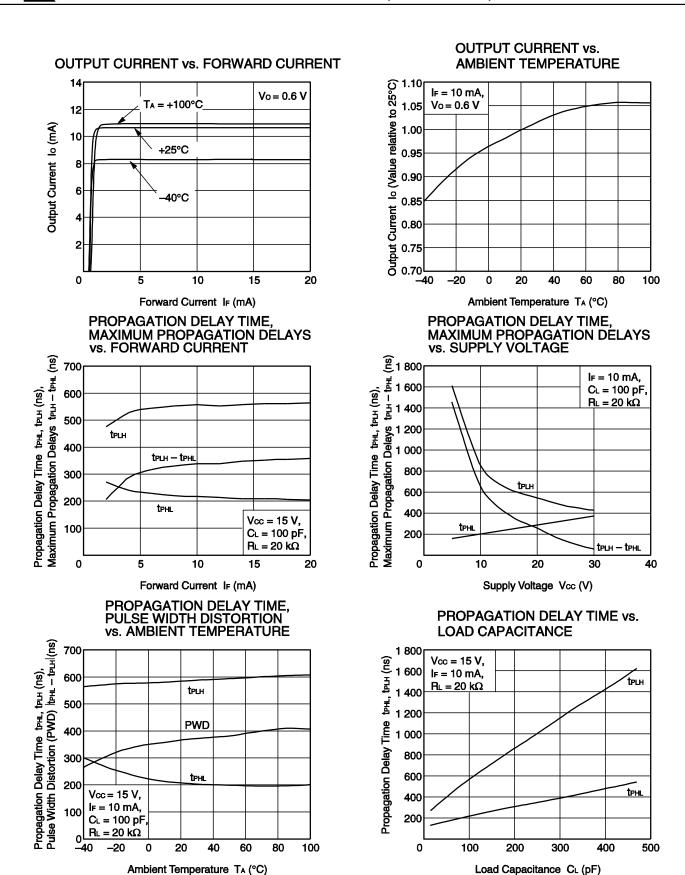
# THRESHOLD INPUT CURRENT vs. AMBIENT TEMPERATURE



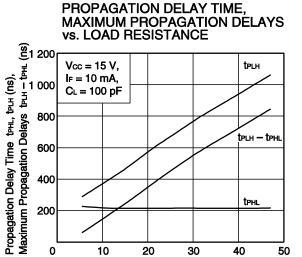
LOW LEVEL OUTPUT VOLTAGE vs. AMBIENT TEMPERATURE



Remark The graphs indicate nominal characteristics.



Remark The graphs indicate nominal characteristics.



**t**PHL

50

40

**Remark** The graphs indicate nominal characteristics.

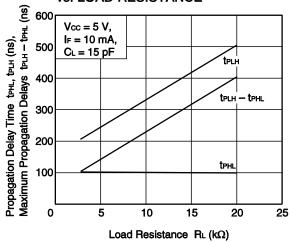
Load Resistance R<sub>L</sub> (kΩ)

20

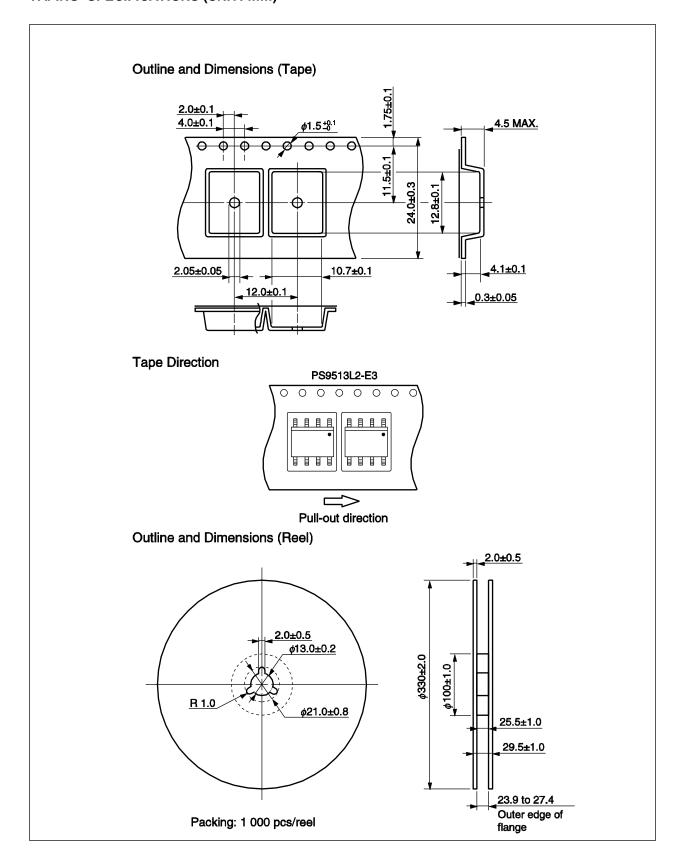
30

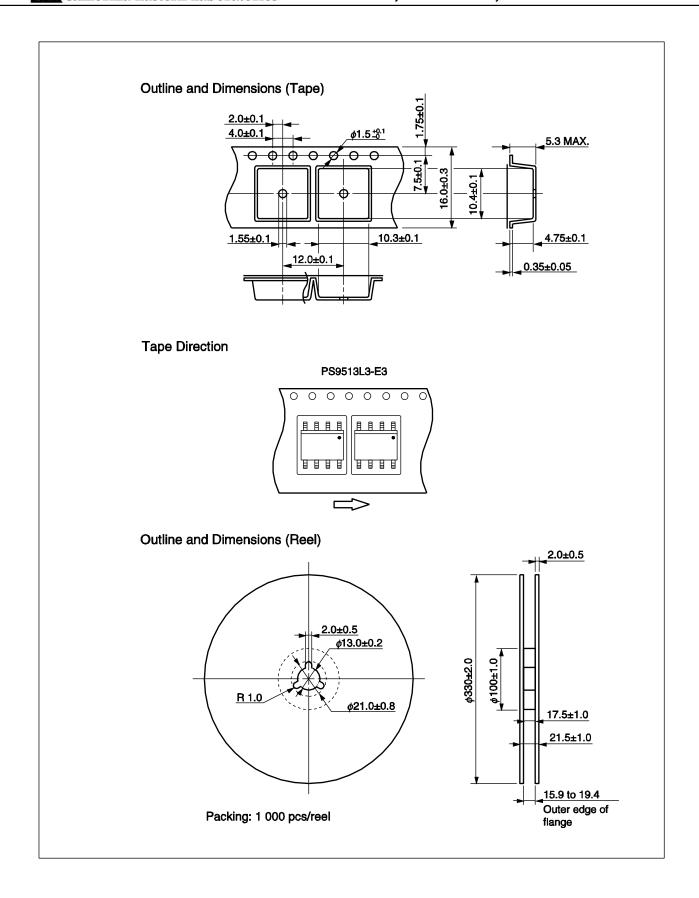
10

# PROPAGATION DELAY TIME MAXIMUM PROPAGATION DELAYS vs. LOAD RESISTANCE

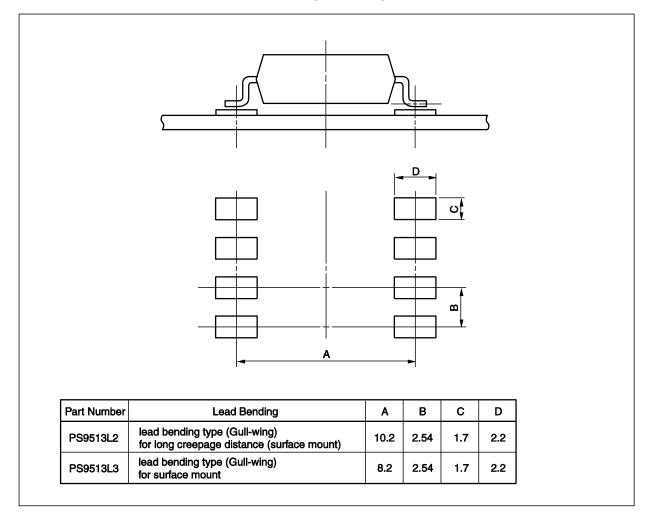


# TAPING SPECIFICATIONS (UNIT: mm)





# RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



#### NOTES ON HANDLING

#### 1. Recommended soldering conditions

#### (1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

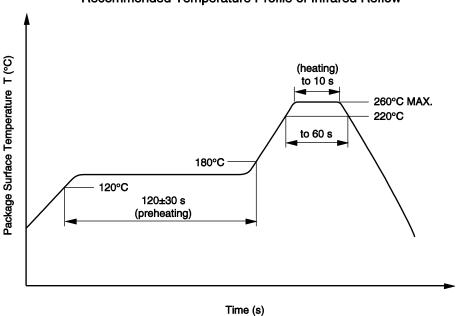
Time of peak reflow temperature
 Time of temperature higher than 220°C
 60 seconds or less

• Time to preheat temperature from 120 to 180°C 120±30 s

Number of reflows
 Three

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### Recommended Temperature Profile of Infrared Reflow



#### (2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

Number of times
 One (Allowed to be dipped in solder including plastic mold portion.)

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

#### (3) Soldering by soldering iron

Peak temperature (lead part temperature) 350°C or below
 Time (each pins) 3 seconds or less

Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

#### (4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

# 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between Vcc-GND at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

# <R> SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Speck	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.5 \times U_{\text{IORM}}, P_{\text{d}} < 5 \text{ pC}$	Ulorm Upr	1 130 1 695	V <sub>peak</sub> V <sub>peak</sub>
Test voltage (partial discharge test, procedure b for all devices) $U_{Pf}=1.875\times U_{\text{IORM}},P_{d}<5p\text{C}$	Upr	2 119	$V_{peak}$
Highest permissible overvoltage	Utr	8 000	Vpeak
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	СТІ	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	Tstg	-55 to +125	°C
Operating temperature range	TA	-40 to +100	°C
Isolation resistance, minimum value $V_{IO}=500~V~dc~at~T_A=25^{\circ}C$ $V_{IO}=500~V~dc~at~T_A~MAX.~at~least~100^{\circ}C$	Ris MIN. Ris MIN.	10 <sup>12</sup> 10 <sup>11</sup>	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I <sub>F</sub> , Psi = 0) Power (output or total power dissipation) Isolation resistance	Tsi Isi Psi	175 400 700	°C mA mW
Vio = 500 V dc at TA = Tsi	Ris MIN.	10 <sup>9</sup>	Ω

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**GaAs Products** 

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
  - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.